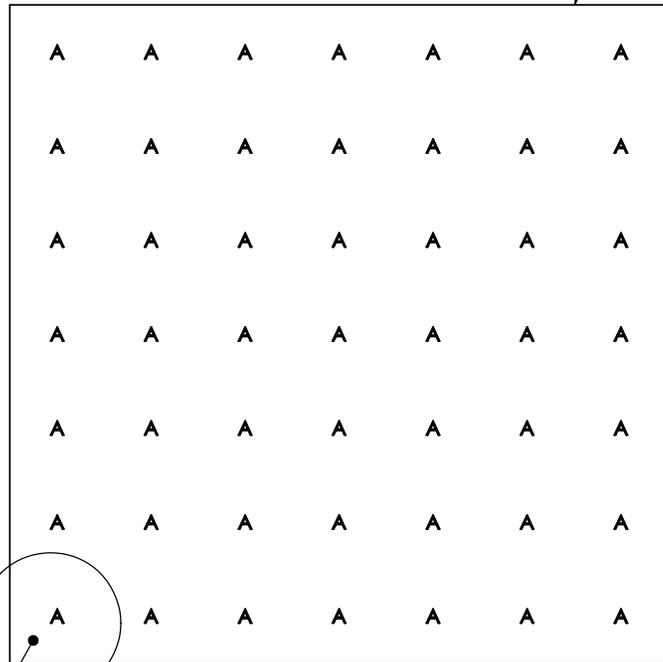


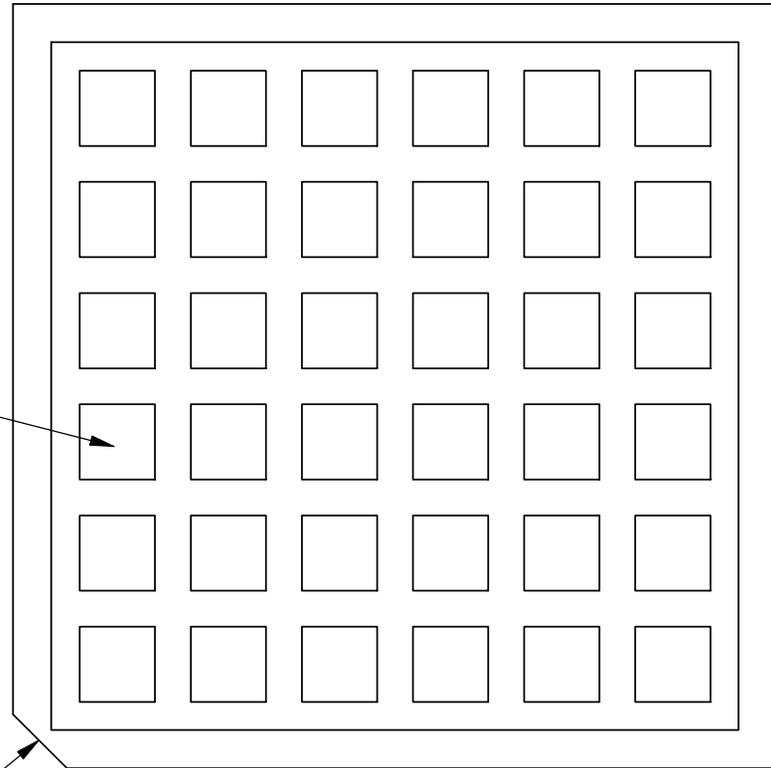
TOP VIEW

SILICON (Si)



EXAMPLE ORIENTATION OF MARKINGS ON WLP

TYPICAL WAFFLE PACK IC CHIP TRAY  
SCALE = 2:1



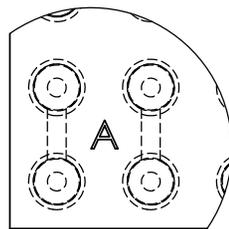
2.00 OR 4.00

NUMBER OF POCKETS WILL CHANGE BASED ON THE SIZE OF THE WLP CHIP

PIN 1 CHAMFER

Notes: (Unless Otherwise Specified).

- 1) EXAMPLE OF TOP SIDE LASER MARKING.
- 2) ORIENT LETTERS FOR LOCATION OF PIN A1 CORNER.
- 3) ALLOWABLE LETTER MARKING: A, F, T, M, L, Y, AND P.
- 4) SINGLE LETTER IS REPEATED MULTIPLE TIMES ACROSS TOP SIDE.
- 5) DAISY CHAIN IS HIDDEN UNDER RESIN ON BALL SIZE.
- 6) TOP SIDE DOES NOT HAVE A DOT FOR LOCATION OF PIN A1.
- 7) LETTERS ARE NOT MARKED ON BOTTOM (BALL) SIDE.



DAISY CHAIN ORIENTATION

DETAIL A  
SCALE 25 : 1

MARKING CODE	
PITCH	LETTER
0.3MM	A
0.4MM	A OR F
0.5MM	A OR P

\* SUBJECT TO CHANGE

APPROVALS		DATE	<b>TopLine</b>			
DRAWN	J. Hines	4/16/2016	TITLE WLP ORIENTATION WAFFLE PACK			
ENG	M. Hart	4/16/2016				
MFG			SCALE 12.5:1	SIZE A	DRAWING NO. 504019	REV A
QA						
CUST			DO NOT SCALE DRAWING		SHEET 1 OF 1	
REVISED						